ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES	burn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declarat	ion of the spencompasse	ubstances s all lowe	within the man r level material	ufacturer list s for which t	ted item. Note: he manufactur	if the item is an a er has engineering	ssembly with lower responsibility.	
21.1 IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials a					s and Mfg Information			
Supplier Information													
Company name* Company unique ID				Unique ID Authority					Res	Response Date*			
ısemi										2023-06-08			
Contact Name	Title - Contact			]	Phone - Contact*				Ema	Email - Contact*			
Product-Env-Stewards	ict-Env-Stewards Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative				Phone - Representative*				Ema	Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Ite	m Number	Mfr Item Name			Effective Date	Version	]	Manufacturing Site		Weight*	UOM	Unit Type	
NUP2	14UPXV5T1G LOW CAP TVS ARI		ARRAY		2023-06-08	08 CN1		CN1		2.678	mg	Each	
Manufacturing Proccess Information		·											
Terminal Plating / Grid Array Material	1 Terminal Base Alloy J-STD-020			Rating	Peak Process Body Temperature Max Time at Pe			at Peak Temp	k Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy 1			1		260		С	30	se	econds 3			
Comments													
evel 1 - maximum time at peak temperature during s	oldering is 10-3	0 seconds											
For more information regarding material composition	n please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.03	mg	Supplier	Silicon (Si)	7440-21-3		0.03	mg	
Lead Frame 1.22	1.22	mg	В	Nickel (Ni)	7440-02-0		0.4941	mg	
			Supplier	Iron (Fe)	7439-89-6		0.6771	mg	
			Supplier	Copper (Cu)	7440-50-8		0.0488	mg	
Mold Compound-Black	1.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.007	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.203	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		0.91	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.14	mg	
Plating	0.003	mg	Supplier	Tin (Sn)	7440-31-5		0.003	mg	
Wire Bond - Cu	0.025	mg	Supplier	Copper (Cu)	7440-50-8		0.025	mg	